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ON Semiconductor®

FSUSB104 — Low-Power, Two-Port, Hi-Speed, USB2.0 (480 Mbps) Switch

Features

Low On Capacitance: 3.7 pF Typical
Low On Resistance: 3.9 Ω Typical

Low Pow er Consumption: 1 μA Maximum

- 15 μ A Maximum I_{CCT} over an Expanded Voltage Range (V_{IN} =1.8 V, V_{CC} =4.3 V)

■ Wide -3 db Bandwidth: > 720 MHz

Packaged in Pb-free 10-Lead UMLP (1.4 x 1.8 mm)

8 kV ESD Rating, >16 kV Pow er/GND ESD Rating

Pow er-Off Protection on All Ports When V_{CC}=0 V

- D+/D- Pins Tolerate up to 5.25 V

Applications

Cell phone, PDA, Digital Camera, and Notebook

■ LCD Monitor, TV, and Set-Top Box

Description

The FSUSB104 is a bi-directional, low-power, two-port, Hi-Speed, USB2.0 switch. Configured as a double-pole, double-throw switch (DPDT) switch, it is optimized for switching between two Hi-Speed (480 Mbps) sources or a Hi-Speed and Full-Speed (12 Mbps) source.

The FSUSB104 is compatible with the requirements of USB2.0 and features an extremely low on capacitance (C_{ON}) of 3.7 pF. The wide bandwidth of this device (720 MHz) exceeds the bandwidth needed to pass the third harmonic, resulting in signals with minimum edge and phase distortion. Superior channel-to-channel crosstalk also minimizes interference.

The FSUSB104 contains special circuitry on the switch VO pins for applications where the V_{CC} supply is powered-off (V_{CC} =0), which allows the device to withstand an over-voltage condition. This device is designed to minimize current consumption even when the control voltage applied to the SEL pin is lower than the supply voltage (V_{CC}). This feature is especially valuable to ultra-portable applications, such as cell phones, allowing for direct interface with the general-purpose VOs of the baseband processor. Other applications include switching and connector sharing in portable cell phones, PDAs, digital cameras, printers, and notebook computers.

Ordering Information

Part Number	Top Mark	Operating Temperature Range	Package
FSUSB104UMX	JF	-40 to +85°C	10-Lead, Quad, Ultrathin Molded Leadless Package (UMLP), 1.4 x 1.8 mm

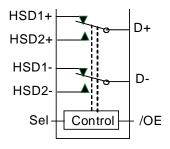


Figure 1. Analog Symbol

Pin Assignments

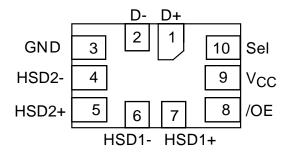


Figure 2. Pin Assignment (Top Through View)

Pin Definitions

Pin #	Name	Description
1	D+	USB Data Bus
2	D-	USB Data Bus
3	GND	Ground
4	HSD2-	Multiplexed Source Inputs
5	HSD2+	Multiplexed Source Inputs
6	HSD1-	Multiplexed Source Inputs
7	HSD1+	Multiplexed Source Inputs
8	/OE	Sw itch Enable
9	Vcc	Supply Voltage
10	Sel	Sw itch Select

Truth Table

Sel	/OE	Function
Х	HIGH	Disconnect
LOW	LOW	D+, D-=HSD1+, HSD1-
HIGH	LOW	D+, D-=HSD2+, HSD2-

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit	
Vcc	Supply Voltage		-0.5	5.6	V
VCNTRL	DC Input Voltage (S, /OE) ⁽¹⁾		-0.5	Vcc	V
V _{SW}	DC Switch I/O Voltage ⁽¹⁾		-0.5	5.25	V
lık	DC Input Diode Current		-50		mA
ЮИТ	DC Output Current			50	mA
T _{STG}	Storage Temperature		-65	+150	°C
		All Pins		7	
ESD	Human Body Model, JEDEC: JESD22-A114	VO to GND		8	kV
ESD		Pow er to GND		16	KV
	Charged Device Model, JEDEC: JESD22-C10		2		

Note:

 The input and output negative ratings may be exceeded if the input and output diode current ratings are observed.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. ON Semiconductor does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
Vcc	Supply Voltage	3.0	4.4	V
VCNTRL	Control Input Voltage (S, /OE) ⁽²⁾	0	Vcc	V
V _{SW}	Sw itch I/O Voltage	-0.5	4.5	V
T _A	Operating Temperature	-40	+85	°C

Note:

2. The control input must be held HIGH or LOW and it must not float.

DC Electrical Characteristics

All typical values are at 25°C unless otherwise specified.

Symbol	Parameter	Conditions	V _{cc} (V)	T _A =- 40°C to +85°C			Units
Symbol	raiametei	Conditions		Min.	Тур.	Max.	Oiiito
Vıĸ	Clamp Diode Voltage	I _{IN} =-18 mA	3.0			-1.2	V
VIH	Input Voltage High		3.0 to 3.6	1.3			V
VIH	i iput voltage i ligit		4.3	1.7			V
VIL	Input Valtage Lew		3.0 to 3.6			0.5	V
V IL	Input Voltage Low		4.3			0.7	V
I _{IN}	Control Input Leakage	V _{SW} =0 to V _{CC}	4.3	-1		1	μA
loz	Off State Leakage	$0 \le Dn$, HSD1n, HSD2n $\le 3.6V$	4.3	-2		2	μΑ
loff	Pow er-Off Leakage Current (All I/O Ports)	V _{SW} =0 V to 4.3 V, V _{CC} =0 V Figure 4	0	-2		2	μΑ
Ron	HS Switch On Resistance (3)	V _{SW} =0.4 V, I _{ON} =-8 mA Figure 3,	3.0		3.9	6.5	Ω
ΔR_{ON}	HS Delta Ron ⁽⁴⁾	V _{SW} =0.4 V, I _{ON} =-8 mA	3.0		0.65		Ω
lcc	Quiescent Supply Current	V _{CNTRL} =0 or V _{CC} , l _{OUT} =0	4.3			1.0	μA
Ісст	Increase in Icc Current per	V _{CNTRL} =2.6 V, V _{CC} =4.3 V	4.3			10.0	μΑ
ICCT	Control Voltage and V _{CC}	V _{CNTRL} =1.8 V, V _{CC} =4.3 V	4.3			15.0	μΑ

Notes:

- 3. Measured by the voltage drop between HSDn and Dn pins at the indicated current through the switch. On resistance is determined by the lower of the voltage on the two (HSDn or Dn ports).
- 4. Guaranteed by characterization. Not tested in production.

AC Electrical Characteristics

All typical value are for V_{CC}=3.3 V at 25°C unless otherwise specified.

Symbol	Parameter	Conditions	V _{cc} (V)	T _A =- 4	Units		
Syllibol				Min.	Тур.	Max.	Ullits
ton	Turn-On Time S, /OE to Output	R_L =50 Ω , C_L =5 pF V_{SW} =0.8 V Figure 5, Figure 6	3.0 to 3.6		13	30	ns
toff	Turn-Off Time S, /OE to Output	R_L =50 Ω , C_L =5 pF V_{SW} =0.8 V Figure 5, Figure 6	3.0 to 3.6		12	25	ns
t _{PD}	Propagation Delay ⁽⁵⁾	C_L =5 pF, R_L =50 Ω Figure 5, Figure 7	3.3		0.25		ns
t _{BBM}	Break-Before-Make	R_L =50 Ω , C_L =5 pF V_{SW1} = V_{SW2} =0.8 V Figure 9	3.0 to 3.6	2.0		6.5	ns
O _{IRR}	Off Isolation	R _L =50 Ω , f=240 MHz Figure 11	3.0 to 3.6		-30		dB
Xtalk	Non-Adjacent Channel Crosstalk	R _L =50 Ω, f=240 MHz Figure 12	3.0 to 3.6		-45		dB
BW	-3db Bandw idth	R_L =50 Ω , C_L =0 pF Figure 10	3.0 to 3.6		720		MHz
DW		R_L =50 Ω , C_L =5 pF Figure 10			550		MHz

Note:

USB Hi-Speed-Related AC Electrical Characteristics

Symbol	Parameter	Conditions	Vcc (V)	T _A =- 40°C to +85°C			Units
	Parameter	Conditions		Min.	Тур.	Max.	Units
t _{SK(P)}	Skew of Opposite Transitions of the Same Output ⁽⁶⁾	C _L =5 pF, R _L =50 Ω Figure 8	3.0 to 3.6		20		ps
tJ	Total Jitter ⁽⁶⁾	R _L =50 Ω , C _L =5 pf, t _R =t _F =500ps (10-90%) at 480 Mbps (PRBS= 2^{15} – 1)	3.0 to 3.6		200		ps

Note:

Capacitance

Symbol	Parameter	Conditions	T _A =- 40°C to +85°C			Units
Jymbor	i arameter	Conditions	Min.	Тур.	Max.	Onits
C _{IN}	Control Pin Input Capacitance	Vcc=0V		1.5		
Con	D+/D- On Capacitance	V _{CC} =3.3 V,/OE=0 V, f=240 MHz Figure 14		3.7		pF
Coff	D1n, D2n Off Capacitance	V _{CC} and /OE=3.3 V See Figure 13		2.0		

^{5.} Guaranteed by characterization. Not tested in production.

^{6.} Guaranteed by characterization. Not tested in production.

Test Diagrams

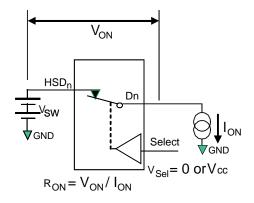
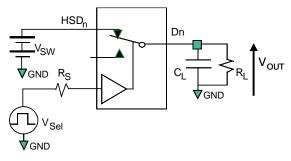


Figure 3. On Resistance



 R_L , R_S , and C_L are functions of the application environment (see AC Tables for specific values) C_L includes test fixture and stray capacitance.

Figure 5. AC Test Circuit Load

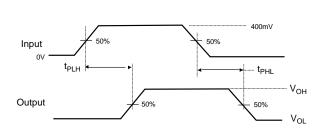
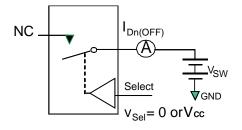


Figure 7. Propagation Delay (t_Rt_F - 500 ps)



**Each switch port is tested separately

Figure 4. Off Leakage

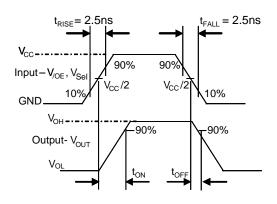


Figure 6. Turn-On / Turn-Off Waveforms

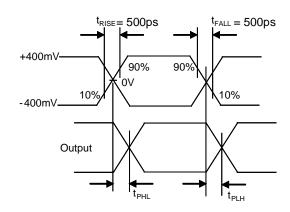


Figure 8. Intra-Pair Skew Test t_{SK(P)}

 $$\rm C_L$$ includes test fixture and stray capacitance. Figure 9. Break-Before-Make Interval Timing

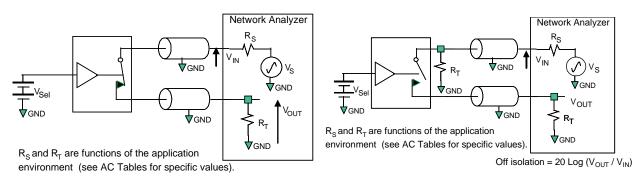


Figure 10. Bandwidth

Figure 11. Channel Off Isolation

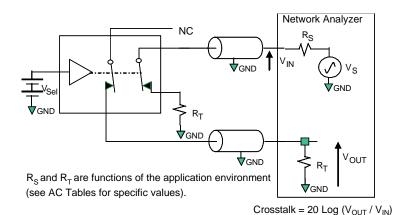


Figure 12. Non-Adjacent Channel-to-Channel Crosstalk

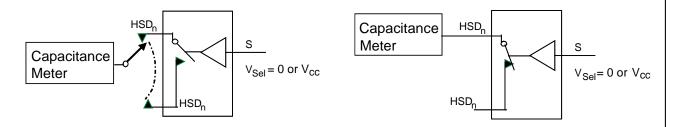
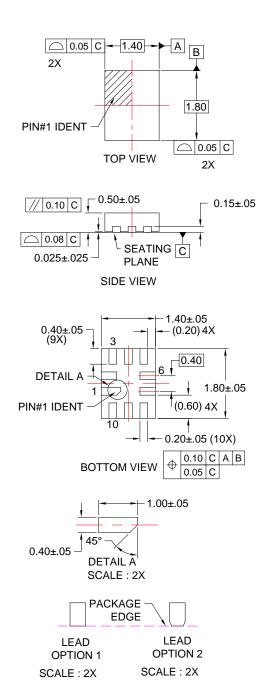
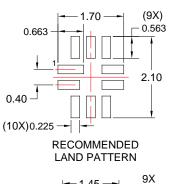


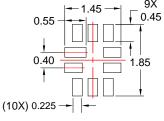
Figure 13. Channel Off Capacitance

Figure 14. Channel On Capacitance

Physical Dimensions







OPTIONAL MINIMIAL TOE LAND PATTERN

NOTES:

- A. PACKAGE DOES NOT CONFORM TO ANY JEDEC STANDARD.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
- E. DRAWING FILENAME: MKT-UMLP10Arev6.

Figure 15. 10-Lead, Ultrathin Molded Leadless Package (UMLP)

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